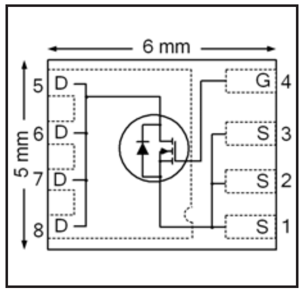
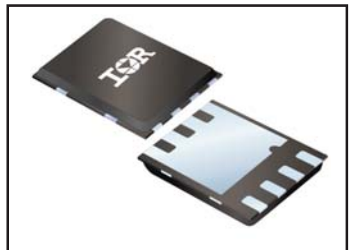
International
IOR Rectifier

IRFH5304PbF

HEXFET® Power MOSFET

V_{DS}	30	V
$R_{DS(on)}$ max (@V_{GS} = 10V)	4.5	mΩ
Q_g (typical)	16	nC
I_D (@$T_{c(Bottom)}$ = 25°C)	79	A





PQFN 5X6 mm

Applications

- Control MOSFET for buck converters

Features and Benefits

Features		Benefits
Low charge (typical 16nC)		Lower Switching Losses
Low Thermal Resistance to PCB (<2.7°C/W)		Increased Power Density
100% Rg tested		Increased Reliability
Low Profile (<0.9 mm)	results in	Increased Power Density
Industry-Standard Pinout	⇒	Multi-Vendor Compatibility
Compatible with Existing Surface Mount Techniques		Easier Manufacturing
RoHS Compliant Containing no Lead, no Bromide and no Halogen		Environmentally Friendlier
MSL1, Industrial Qualification		Increased Reliability

Orderable part number	Package Type	Standard Pack		Note
		Form	Quantity	
IRFH5304TRPBF	PQFN 5mm x 6mm	Tape and Reel	4000	
~~IRFH5304TR2PBF~~	~~PQFN 5mm x 6mm~~	~~Tape and Reel~~	~~400~~	EOL notice # 259

Absolute Maximum Ratings

	Parameter	Max.	Units
V_{DS}	Drain-to-Source Voltage	30	V
V_{GS}	Gate-to-Source Voltage	± 20	
I_D @ T_A = 25°C	Continuous Drain Current, V_{GS} @ 10V	22	A
I_D @ T_A = 70°C	Continuous Drain Current, V_{GS} @ 10V	17	
I_D @ $T_{C(Bottom)}$ = 25°C	Continuous Drain Current, V_{GS} @ 10V	79	
I_D @ $T_{C(Bottom)}$ = 100°C	Continuous Drain Current, V_{GS} @ 10V	50	
I_{DM}	Pulsed Drain Current ①	320	
P_D @T_A = 25°C	Power Dissipation ⑤	3.6	W
P_D @ $T_{C(Bottom)}$ = 25°C	Power Dissipation ⑤	46	
	Linear Derating Factor ⑤	0.029	W/°C
T_J T_{STG}	Operating Junction and Storage Temperature Range	-55 to + 150	°C

Notes ① through ⑥ are on page 8

  Submit Datasheet Feedback May 14, 2014

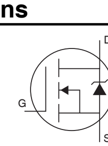
Static @ T_J = 25°C (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
BV_{DSS}	Drain-to-Source Breakdown Voltage	30	——	——	V	V_{GS} = 0V, I_D = 250μA
$\Delta BV_{DSS}/\Delta T_J$	Breakdown Voltage Temp. Coefficient	——	0.02	——	V/°C	Reference to 25°C, I_D = 1mA
$R_{DS(on)}$	Static Drain-to-Source On-Resistance	——	3.8	4.5	mΩ	V_{GS} = 10V, I_D = 47A ③
		——	5.8	6.8		V_{GS} = 4.5V, I_D = 47A ③
$V_{GS(th)}$	Gate Threshold Voltage	1.35	1.8	2.35	V	V_{DS} = V_{GS}, I_D = 50μA
$\Delta V_{GS(th)}$	Gate Threshold Voltage Coefficient	——	-6.6	——	mV/°C	
I_{DSS}	Drain-to-Source Leakage Current	——	——	5.0	μA	V_{DS} = 24V, V_{GS} = 0V
		——	——	150		V_{DS} = 24V, V_{GS} = 0V, T_J = 125°C
I_{GSS}	Gate-to-Source Forward Leakage	——	——	100	nA	V_{GS} = 20V
	Gate-to-Source Reverse Leakage	——	——	-100		V_{GS} = -20V
gfs	Forward Transconductance	88	——	——	S	V_{DS} = 15V, I_D = 47A
Q_g	Total Gate Charge	——	41	——	nC	V_{GS} = 10V, V_{DS} = 15V, I_D = 49A
Q_g	Total Gate Charge	——	16	24	nC	
Q_{gs1}	Pre-Vth Gate-to-Source Charge	——	3.6	——		V_{DS} = 15V
Q_{gs2}	Post-Vth Gate-to-Source Charge	——	2.7	——		V_{GS} = 4.5V
Q_{gd}	Gate-to-Drain Charge	——	5.8	——		I_D = 47A
Q_{godr}	Gate Charge Overdrive	——	3.9	——		See Fig.17 & 18
Q_{sw}	Switch Charge (Q_{gs2} + Q_{gd})	——	8.5	——		
Q_{oss}	Output Charge	——	9.8	——	nC	V_{DS} = 16V, V_{GS} = 0V
R_G	Gate Resistance	——	1.2	——	Ω	
$t_{d(on)}$	Turn-On Delay Time	——	13	——	ns	V_{DD} = 15V, V_{GS} = 4.5V
t_r	Rise Time	——	25	——		I_D = 47A
$t_{d(off)}$	Turn-Off Delay Time	——	12	——		R_G=1.8Ω
t_f	Fall Time	——	6.6	——		See Fig.15
C_{iss}	Input Capacitance	——	2360	——	pF	V_{GS} = 0V
C_{oss}	Output Capacitance	——	510	——		V_{DS} = 10V
C_{rss}	Reverse Transfer Capacitance	——	220	——		f = 1.0MHz

Avalanche Characteristics

	Parameter	Typ.	Max.	Units
E_{AS}	Single Pulse Avalanche Energy ②	——	46	mJ
I_{AR}	Avalanche Current ①	——	47	A

Diode Characteristics

	Parameter	Min.	Typ.	Max.	Units	Conditions
I_S	Continuous Source Current (Body Diode)	——	——	79	A	MOSFET symbol showing the integral reverse p-n junction diode. 
I_{SM}	Pulsed Source Current (Body Diode) ①	——	——	320		
V_{SD}	Diode Forward Voltage	——	0.71	——	V	T_J = 25°C, I_S = 5A, V_{GS} = 0V ③
V_{SD}	Diode Forward Voltage	——	——	1.0	V	T_J = 25°C, I_S = 47A, V_{GS} = 0V ③
t_{rr}	Reverse Recovery Time	——	19	29	ns	T_J = 25°C, I_F = 47A, V_{DD} = 15V
Q_{rr}	Reverse Recovery Charge	——	44	66	nC	di/dt = 300A/μs ③
t_{on}	Forward Turn-On Time	Time is dominated by parasitic Inductance				

Thermal Resistance

	Parameter	Typ.	Max.	Units
$R_{\theta JC}$ (Bottom)	Junction-to-Case ④	——	2.7	°C/W
$R_{\theta JC}$ (Top)	Junction-to-Case ④	——	15	
$R_{\theta JA}$	Junction-to-Ambient ⑤	——	35	
$R_{\theta JA}$ (<10s)	Junction-to-Ambient ⑤	——	22	

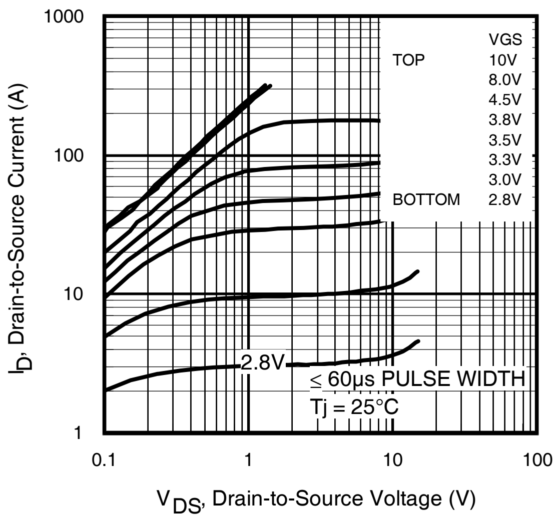


Fig 1. Typical Output Characteristics

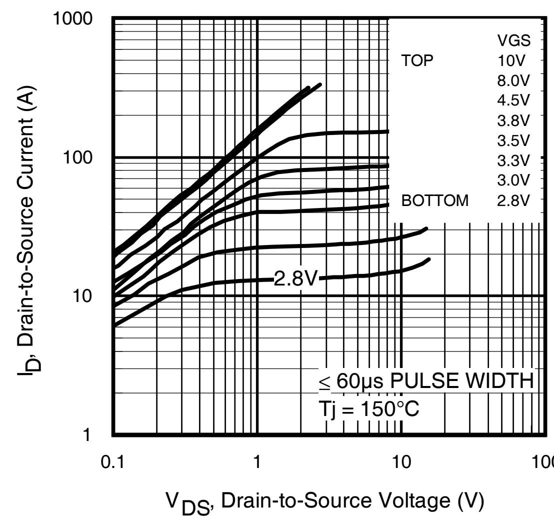


Fig 2. Typical Output Characteristics

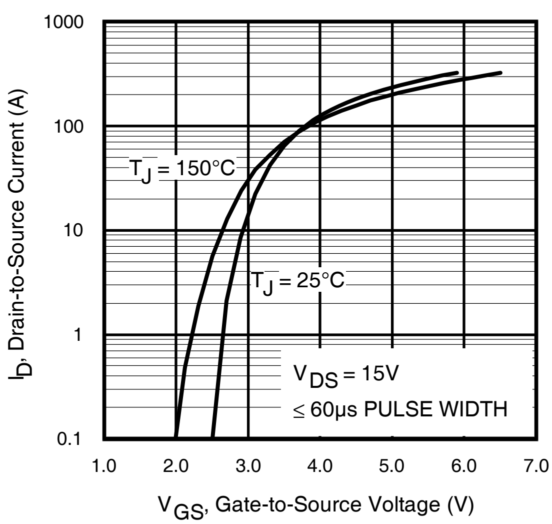


Fig 3. Typical Transfer Characteristics

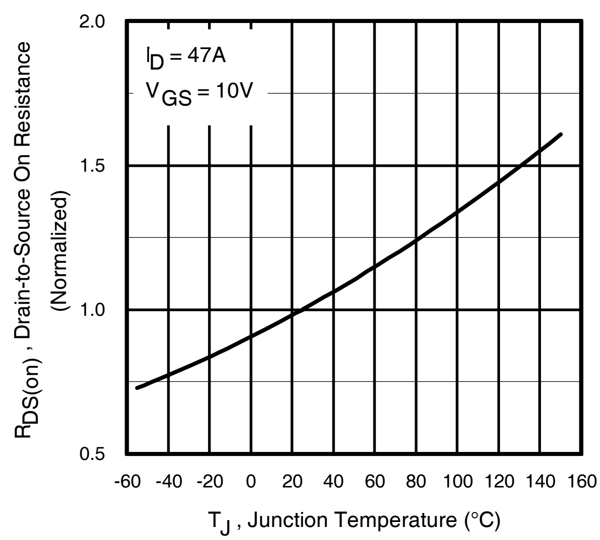


Fig 4. Normalized On-Resistance Vs. Temperature

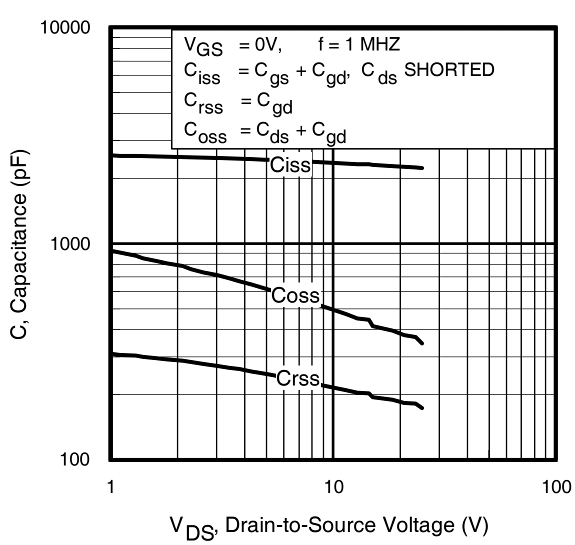


Fig 5. Typical Capacitance Vs.Drain-to-Source Voltage

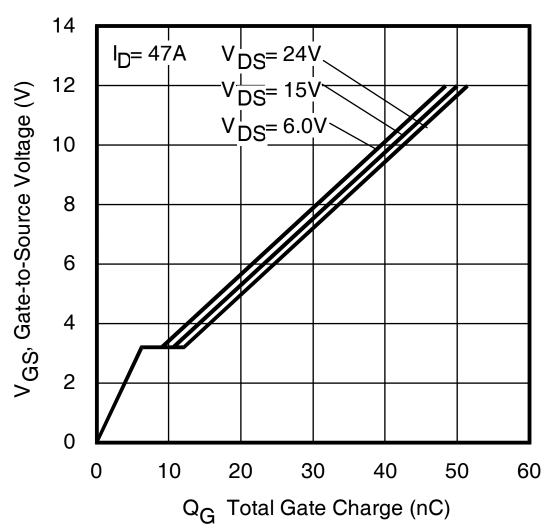


Fig 6. Typical Gate Charge Vs.Gate-to-Source Voltage

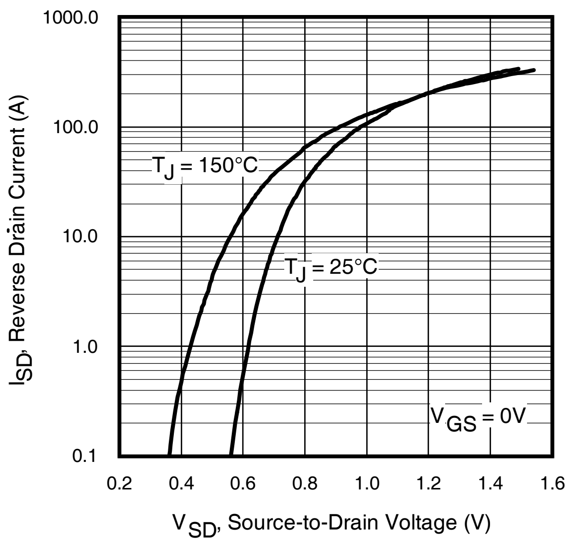


Fig 7. Typical Source-Drain Diode Forward Voltage

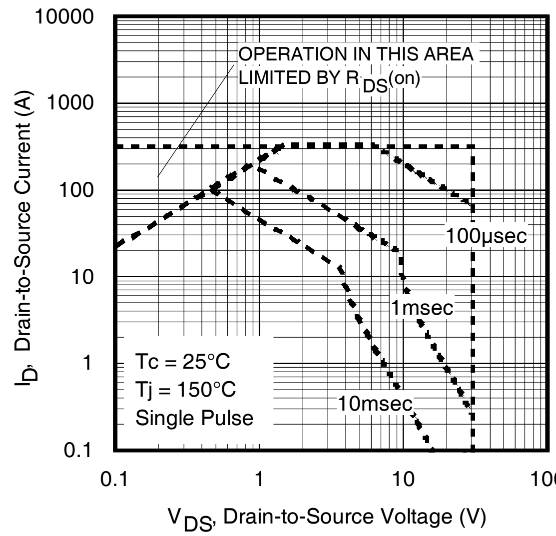


Fig 8. Maximum Safe Operating Area

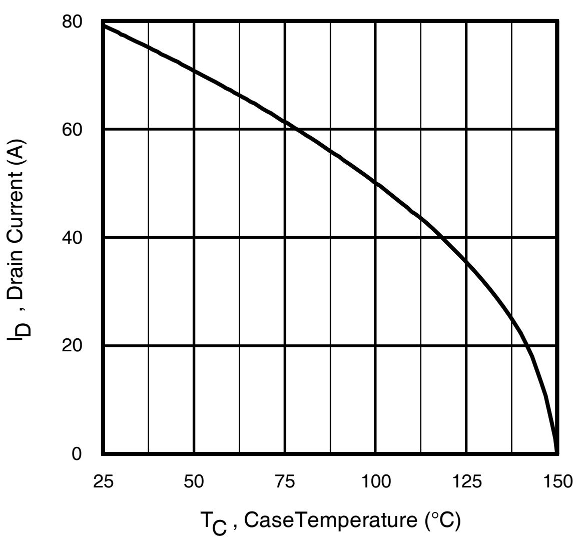


Fig 9. Maximum Drain Current Vs. Case (Bottom) Temperature

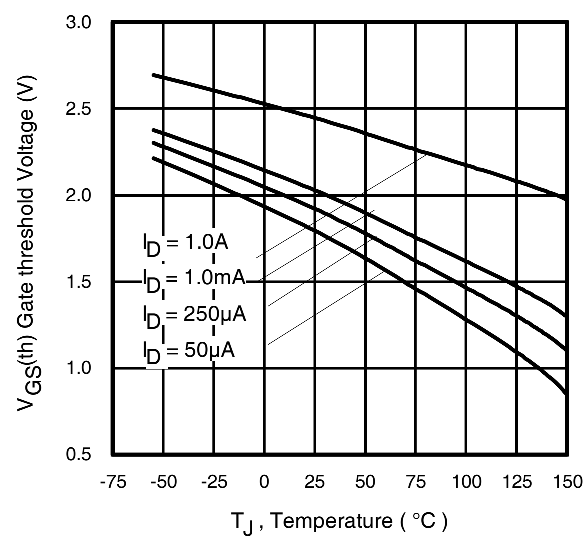


Fig 10. Threshold Voltage Vs. Temperature

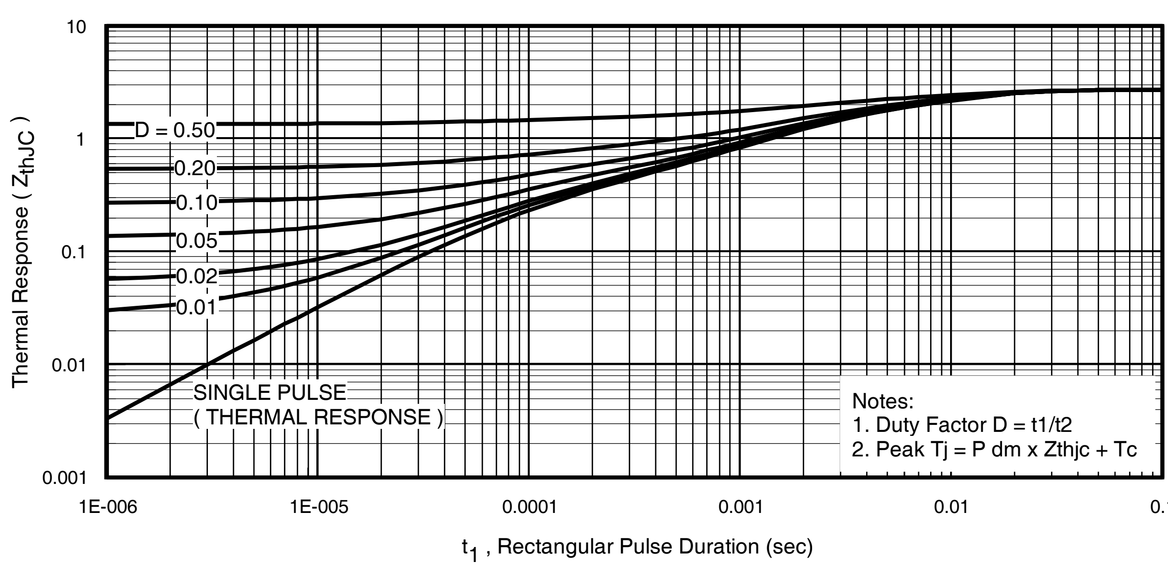


Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Case (Bottom)

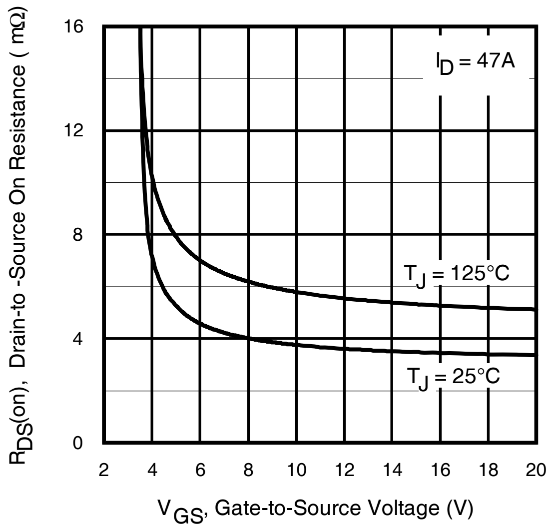


Fig 12. On-Resistance vs. Gate Voltage

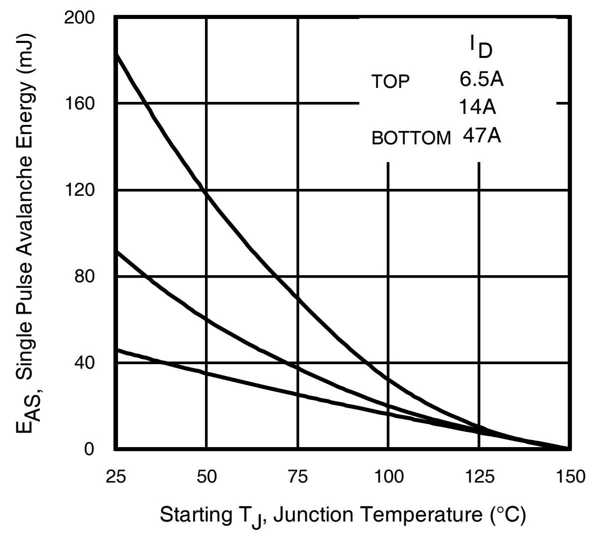


Fig 13. Maximum Avalanche Energy vs. Drain Current

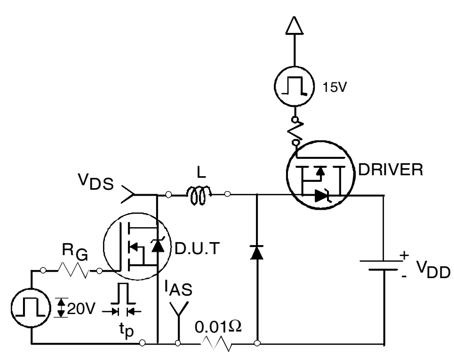


Fig 14a. Unclamped Inductive Test Circuit

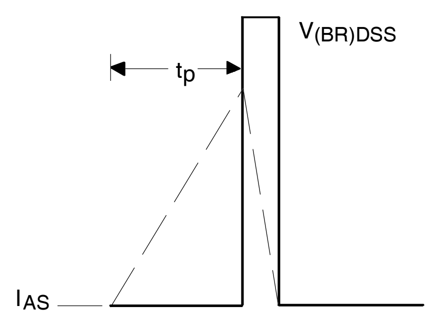


Fig 14b. Unclamped Inductive Waveforms

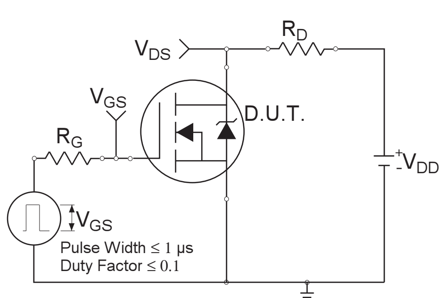


Fig 15a. Switching Time Test Circuit

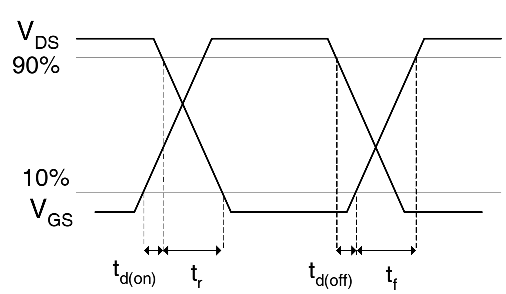


Fig 15b. Switching Time Waveforms

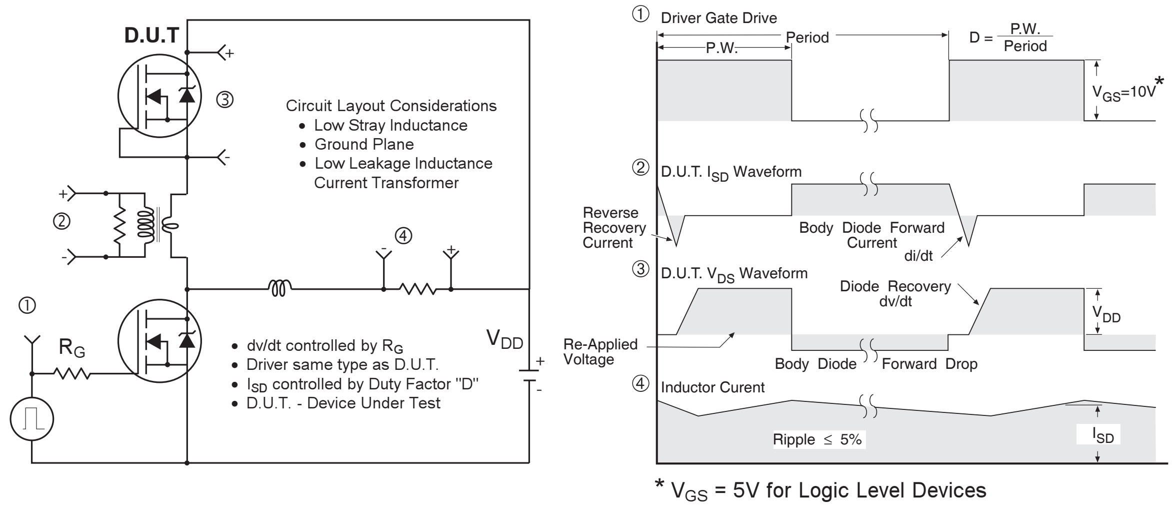


Fig 16. Peak Diode Recovery dv/dt Test Circuit for N-Channel HEXFET® Power MOSFETs

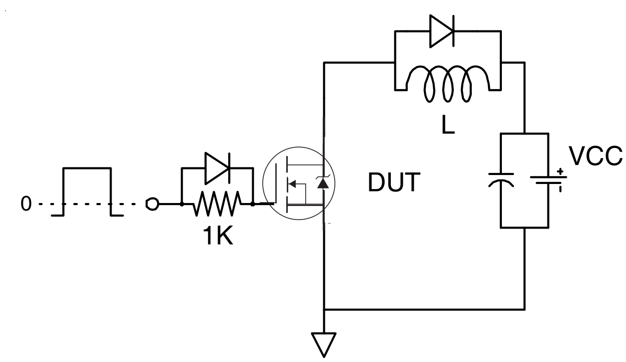


Fig 17. Gate Charge Test Circuit

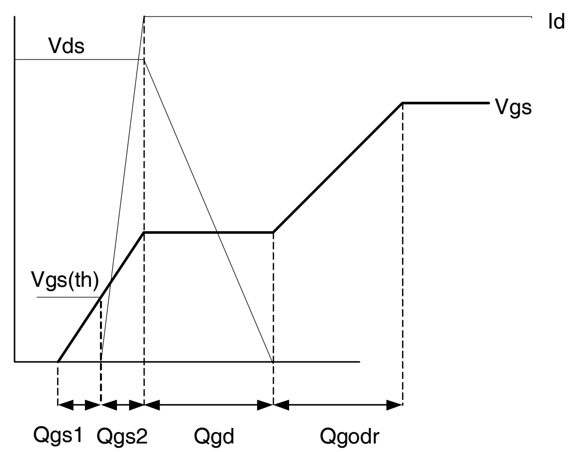
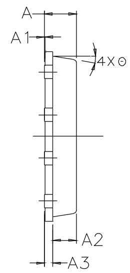
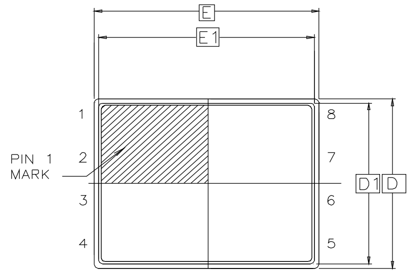


Fig 18. Gate Charge Waveform

PQFN 5x6 Outline "B" Package Details

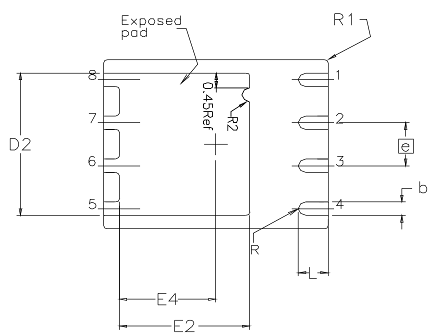


SIDE VIEW



TOP VIEW

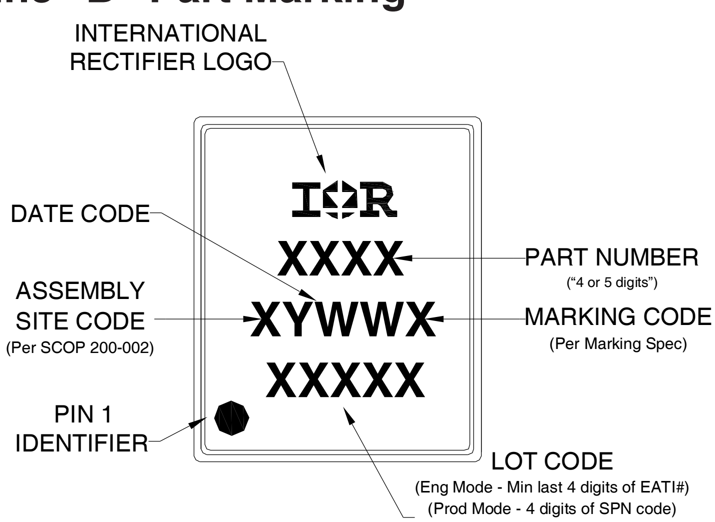
DIM / SYMBOL	MIN	NOM	MAX
A	0.800	0.830	1.05
A1	0.000	0.020	0.050
A2	0.580	0.630	0.680
A3	0.254 REF		
Θ	0°	10°	12°
b	0.350	0.400	0.470
D	4.850	5.000	5.150
D1	4.675	4.750	5.000
D2	3.700	4.210	4.300
e	1.270 BSC		
E	5.850	6.000	6.150
E1	5.675	5.750	6.000
E2	3.380	3.480	3.760
E4	2.480	2.580	2.680
L	0.550	0.800	0.900
R	0.200 REF		
R1	0.100 REF		
R2	0.150	0.200	0.250



BOTTOM VIEW

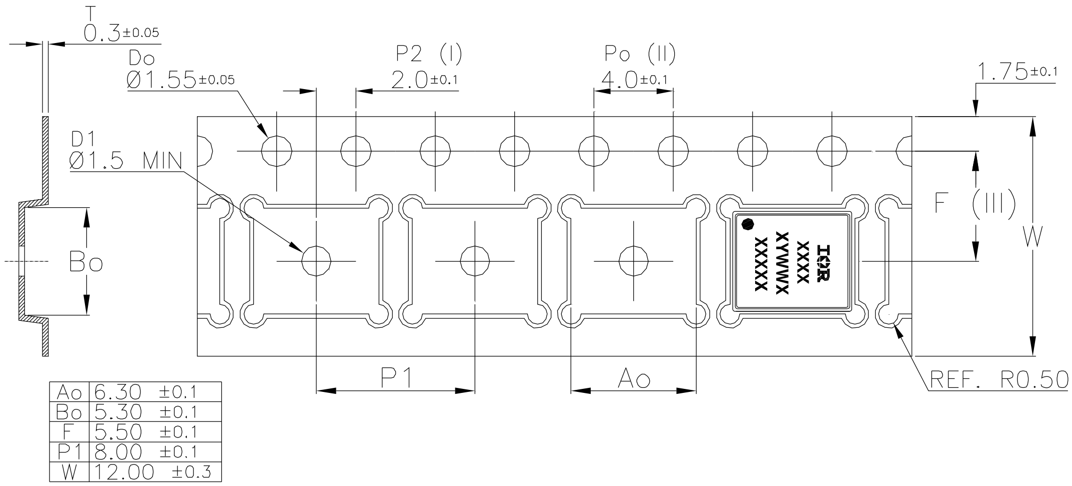
For footprint and stencil design recommendations, please refer to application note AN-1154 at http://www.irf.com/technical-info/appnotes/an-1154.pdf

PQFN 5x6 Outline "B" Part Marking



Note: For the most current drawing please refer to IR website at: http://www.irf.com/package/

PQFN Tape and Reel



Note: For the most current drawing please refer to IR website at: http://www.irf.com/package/

Qualification information[†]

Qualification level	Industrial[††] (per JEDEC JESD47F [†††] guidelines)	
Moisture Sensitivity Level	PQFN 5mm x 6mm	MSL1 (per JEDEC J-STD-020D[†††])
RoHS compliant	Yes	

† Qualification standards can be found at International Rectifier's web site http://www.irf.com/product-info/reliability

†† Higher qualification ratings may be available should the user have such requirements. Please contact your International Rectifier sales representative for further information: http://www.irf.com/whoto-call/salesrep/

††† Applicable version of JEDEC standard at the time of product release.

Notes:

① Repetitive rating; pulse width limited by max. junction temperature.
② Starting T_J = 25°C, L = 0.041mH, R_G = 50Ω, I_{AS} = 47A.
③ Pulse width ≤ 400μs; duty cycle ≤ 2%.
④ R_θ is measured at T_J of approximately 90°C.
⑤ When mounted on 1 inch square 2 oz copper pad on 1.5x1.5 in. board of FR-4 material.

Revision History

Date	Comment
5/14/2014	• Updated ordering information to reflect the End-Of-life (EOL) of the mini-reel option (EOL notice #259) • Updated Package outline on page 7. • Updated data sheet based on corporate template.

International Rectifier

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